Core Solders “Non-Flux Sputtering Products”

Improved ALMIT FLUX SR-37 to prevent the scattering of both flux and solder balls in the soldering process.

SR-37

1. Solderability at the initial soldering stage is specially excellent, following SR-34 SUPER that has better wettability and workability.
2. Sputtered flux amount is reduced to about 80-90%, as compared with that of the ordinal Almit products.
3. Evolution of much fume and smell during the soldering process is completely prevented.

Examples of application: SMD-Glass solder Single-sided and through-hole substrates.

Comparison of spread areas
- Core solder dia.: 0.88, solders iron temp.: 320°C, 350°C, 380°C, Feeding amount: 50 mm
- Feeding speed: 10 mm/sec, Holding time: 0.5 sec, Sample piece: 1 piece <20 spots soldered>

Comparison of sputtered flux
- Core solder dia.: 0.88, solders iron temp.: 320°C, 350°C, 380°C, Feeding amount: 50 mm
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Comparison of spread areas on the Cu plate as compared with that of other makers' products.

SR-37

Other makers’ products (comparison reference)

Comparison of sputtered flux

GUMMIX-19 Series
GUMMIX-19CH / GUMMIX-SB RMA

1. Possible to decrease all flux sputtering, ending zero value.
2. Non-peel off of flux residue on Cu plate after soldered.
3. Applicable to many parts and devices, such as optical Pickup, Relay, SW, and flexible substrates, etc.

Examples of application: SMD-Glass solder, Pickup, Relay, and SW.

Comparison of sputtered flux

Product name component for Core Solder

(Flux name: alloy type, flux content, core solder diameter)

Core Solder products specification

<table>
<thead>
<tr>
<th>Core name</th>
<th>Alloy type</th>
<th>Flux content</th>
<th>Holding time</th>
<th>Core solder diameter</th>
</tr>
</thead>
<tbody>
<tr>
<td>SR-37</td>
<td>U/Mg-48</td>
<td>3.5%</td>
<td>217°C</td>
<td>0.3, 0.36, 0.5, 0.65, 0.8, 1, 1.2, 1.4</td>
</tr>
<tr>
<td>GUMMIX-19CH</td>
<td>U/Mg-48</td>
<td>3.5%</td>
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</tr>
<tr>
<td>GUMMIX-SB RMA</td>
<td>U/Mg-48</td>
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<td>217°C</td>
<td>0.3, 0.36, 0.5, 0.65, 0.8, 1, 1.2, 1.4</td>
</tr>
</tbody>
</table>

GUMMIX-19 Series

Non-peel off of the flux residues

*U/Mg-48 has been approved for JP Pfi No.3027441 and US Pfi No.5527428. *If the ordered core solder diameter is out of stock, please contact our sales representatives.

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